Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (L^2 - π -MOSV)

2SK2615

Applications

• Low drain-source ON resistance : RDS (ON) = 0.23Ω (typ.) High forward transfer admittance $|Y_{fs}| = 2.0 \text{ S (typ.)}$: $I_{DSS} = 100 \, \mu A \, (max) \, (V_{DS} = 60 \, V)$ Low leakage current Enhancement mode : $V_{th} = 0.8 \sim 2.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Absolute Maximum Ratings (Ta = 25°C)

Characteri	stics	Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	60	V	
Drain-gate voltage (R	_{GS} = 20 kΩ)	V_{DGR}	60	V	
Gate-source voltage	Gate-source voltage		±20	V	
Drain current	DC (Note 1)	I _D	2	Α	
	Pulse (Note 1)	I_{DP}	6	^	
Drain power dissipatio	n	PD	0.5	W	
Drain power dissipation (Note 2)		P_{D}	1.5	W	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: Mounted on a ceramic substrate (25.4 mm × 25.4 mm × 0.8 mm)

Note 3: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

DC-DC Converter, Relay Drive and Motor Drive

4.6MAX. 1.7MAX.	1,6MAX. 0.4±0.05
11.	80.0+ 80.00+ 4.2MAX.
<u>т т т</u> т т т т т т т т т т т т т т т т	1.5±0.1
2. DRAIN (HEAT SINK) 3. SOURCE	30

Weight: 0.05 g (typ.)

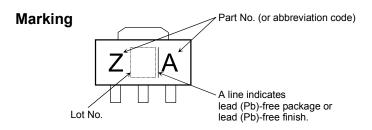
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JEDEC JEITA TOSHIBA

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient	R _{th (ch-a)}	250	°C/W

This transistor is an electrostatic-sensitive device. Please handle with caution.



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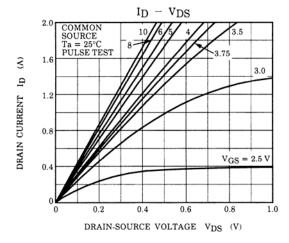
Electrical Characteristics (Ta = 25°C)

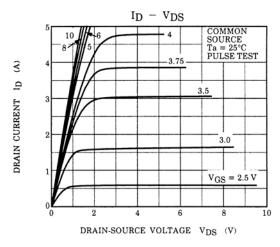
Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	irrent	I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	_	_	±10	μA
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 60 V, V _{GS} = 0 V	_	_	100	μA
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	60	_	_	٧
Gate threshold v	oltage/	V_{th}	V _{DS} = 10 V, I _D = 1 mA	0.8	_	2.0	V
Drain-source ON resistance		P-a (a)	VGS = 4 V, ID = 1 A	_	0.33	0.44	Ω
		R _{DS} (ON)	VGS = 10 V, ID = 1 A	_	0.23	0.30	1 12
Forward transfer	r admittance	Y _{fs}	V _{DS} = 10 V, I _D = 1 A	1.0	2.0	_	S
Input capacitano	e	C _{iss}		_	150	_	
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	25	_	pF
Output capacitance		Coss		_	70	_	
Switching time	Rise time	t _r	V_{GS} V_{OV} V_{OU} V_{OU} V_{OU} V_{OU} V_{OU} V_{OU} V_{OU}	_	25	_	
	Turn-on time	t _{on}		_	30	_	- ns
	Fall time	t _f		_	50	_	
	Turn-off time	t _{off}	Duty $\leq 1\%$, $t_{\rm W} = 10 \mu \rm s$	_	150	_	
			_	6.0			
		Qgs	$V_{DD} \approx 48 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 2 \text{ A}$	_	4.6	_	nC
		Q _{gd}		_	1.4	_	

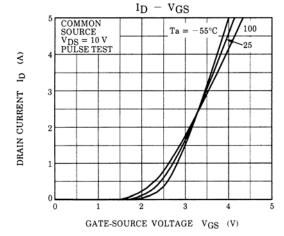
Source-Drain Ratings and Characteristics (Ta = 25°C)

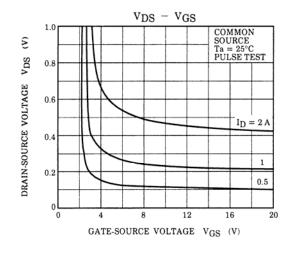
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	2	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	6	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 2 A, V _{GS} = 0 V	_	_	-1.5	V
Reverse recovery time	t _{rr}	I _{DR} = 2 A, V _{GS} = 0 V dI _{DR} / dt = 50 A / µs	_	100		ns
Reverse recovery charge	Q _{rr}	dl _{DR} / dt = 50 A / μs	ı	40	ı	nC

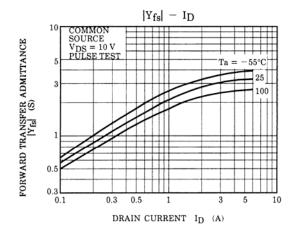
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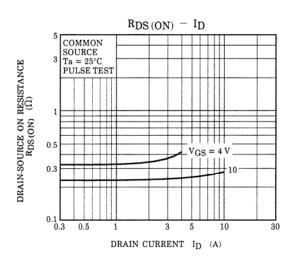


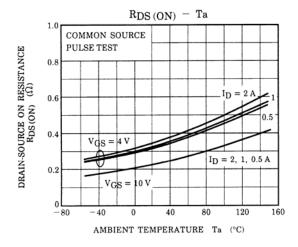


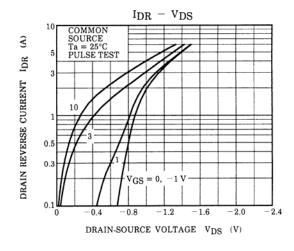


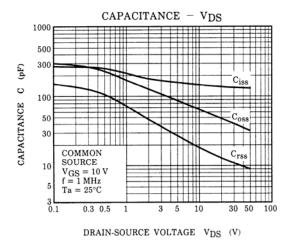


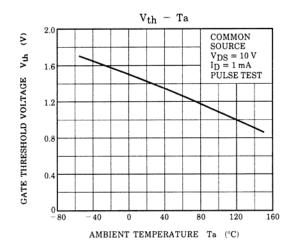


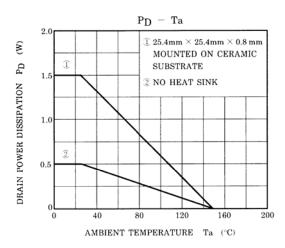


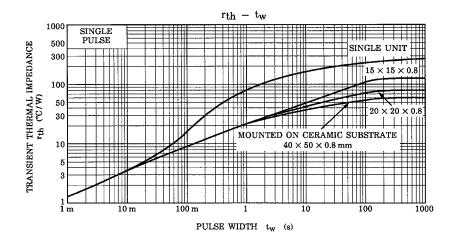


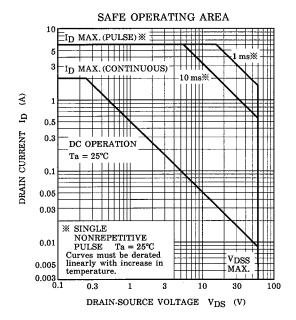












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